

SSC8L62GN6

N-Channel Enhanced MOSFET

> Features

VDS	VGS	RDSON Typ.	ID
60)/	1201/	8mR@10V	604
60V	±20V	12mR@4V5	60A

> Description

This device is N-Channel enhancement MOSFET. Uses SGT technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

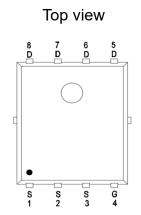
100% UIS Tested.

- > Applications
- DC/DC converters
- Power supplies
- Motor Drive Control
- Synchronous rectification

> Ordering Information

Device	Package	Shipping	
SSC8L62GN6	PDFN5X6	5000/Reel	

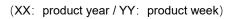
Pin configuration





B B B B SS 8L62GN6 XXYY • • •

Marking



> Absolute Maximum Ratings(T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit		
VDSS	Drain-to-Source Vol	tage	60	V	
V _{GSS}	Gate-to-Source Volt	tage	±20	V	
1	Continuous Duoin Curront d	Tc=25℃		٨	
lD	Continuous Drain Current ^d	Tc=100°C	31	A	
1		T _A =25℃	19		
DSM	Continuous Drain Current ^a	T _A =70°C	14	A	
I _{DM}	Pulsed Drain Current ^b		240	А	
6	Tc=25℃		46		
PD	Power Dissipation ^c	Tc=100°C	18	W	
_	Power Dissipation ^a $T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$		5	14/	
Pdsm			3.2	W	
las	Avalanche Current ^b L=0.5mH Single Pulse		18	А	
Eas	Avalanche Energy ^b L=0.5mH Single Pulse		81	mJ	
TJ	Operation junction temperature		-55~150	~	
Tstg	Storage temperature range		-55~150	°C	

> Thermal Resistance Ratings($T_A=25^{\circ}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
R _{θJA}	Junction-to-Ambient Thermal Resistance ^a	25	°C/W
R _{θJC}	Junction-to-Case Thermal Resistance	2.7	C/ VV

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25°C.The value in any given application depends on the user is specific board design. The power dissipation is based on the t ≤ 10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

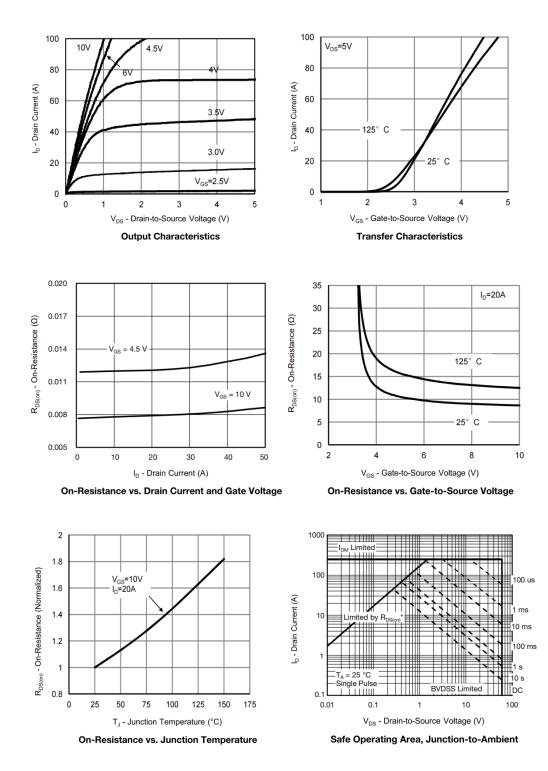


Electronics Characteristics(T_A=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	VGS=0V ,ID=250uA	60			v
$V_{GS \ (th)}$	Gate Threshold Voltage	VDS=VGS ,ID=250uA	1.0	1.8	2.4	V
D	Drain-Source On-	VGS=10V , ID=30A		8	9.5	D
$R_{DS(on)}$	Resistance	VGS=4.5V , ID=20A		12.5	15.5	mR
I _{DSS}	Zero Gate Voltage Drain Current	VDS=60V ,VGS=0V			1	uA
I _{GSS}	Gate-Source leak current	VGS=±20V ,VDS=0V			±100	nA
G _{FS}	Transconductance	VDS=5V ,ID=20A		30		S
V_{SD}	Forward Voltage	VGS=0V , IS=20A		0.8	1.3	V
Rg	Gate Resistance	VDS=0V, f=1MHz		1.4		R
Ciss	Input Capacitance			960		
Coss	Output Capacitance	VDS=30V , VGS=0V,		380		pF
Crss	Reverse Transfer Capacitance	f=1MHz		22		. Pi
T _{D(ON)}	Turn-on delay time			5.4		
Tr	Rise time	VGS=10V, RL=1.5R		18.3		
Td(OFF)	Turn-off delay time	VDS=30V , RG=3R		17.4		ns
Tf	Fall time			18.4		
Q_{G}	Total Gate Charge			16		
Q _{GS}	Gate Source Charge	VGS=10V, VDS=30V		4.4		nC
Qgd	Gate Drain Charge	- ID=20A		2.3		
Trr	Diode Recovery Time	IF=20A , di/dt=500A/us		22		ns
Qrr	Diode Recovery Charge	IF=20A , di/dt=500A/us		54		nC

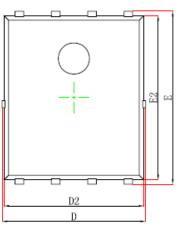


> Typical Characteristics(T_A=25°C unless otherwise noted)

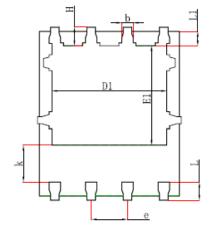




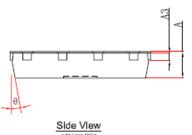
Package Information







<u>Bottom Vlew</u> [背视图]



Side	V	lew	
[側社	则	冬]	

Symbol	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254	1REF	0.010	DREF
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP		0.050TYP	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
Н	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°



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